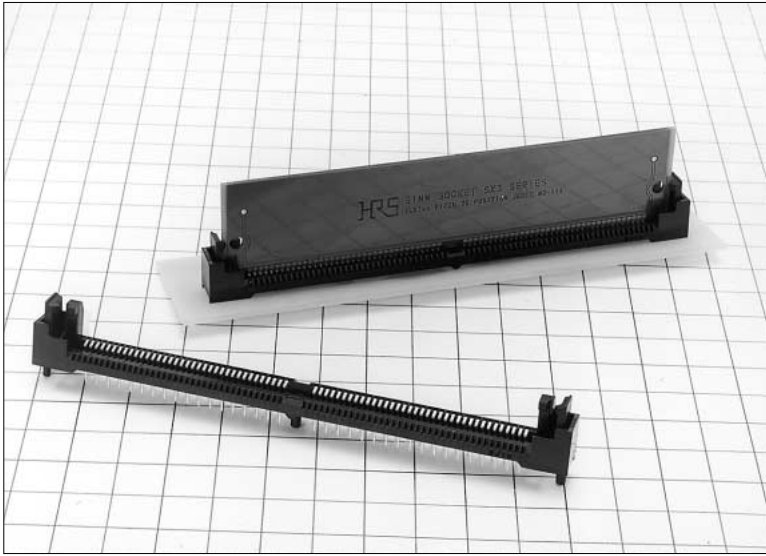


1.27mm Pitch SIMM Socket

SX3 Series



SX3LE-72S-1.27DSA

■ Features

1. JEDEC Standard MO-116

This socket is suitable to JEDEC standard 1.27mm pitch 72pos. memory module PC board.

2. Achieves High Reliability

New concept "mold latch system" achieves high reliability for safe handling.

3. Greatly Improves Operation Durability

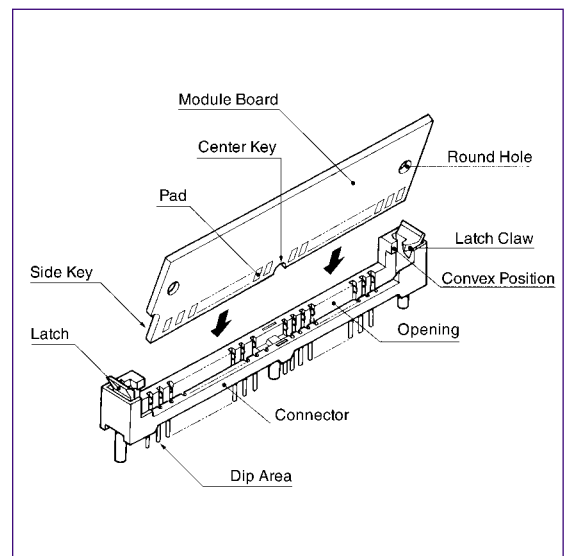
The mold latch system has greatly improved the operation durability using the FEM analysis.

4. Achieves High Performance

Contacts achieves high reliability in contact with smooth rolling areas.

5. Secures Stable Contact Areas

The contact floating mechanism and structure to reduce the board warpage secures stable contact areas.



■ Applications

Note PC, workstations, business machines, measuring instruments, etc.

■ Product Specifications

Rating	Operating Temperature Range	-55°C to 85°C	Storage Temperature Range	-55°C to +85°C	
	Voltage rating	100V AC			
	Current rating	1A			

Item	Specification	Condition
1. Contact Resistance	20m ohms min.	100mA DC
2. Insulation Resistance	1000M ohms min.	500V DC
3. Withstanding voltage	No flashover or insulation breakdown.	500V AC / 1 minute
4. Vibration	No electrical discontinuity of 1μs or more	Frequency: 10 to 55 Hz, single amplitude of 0.75 mm, 50 minutes in each of the 3 directions.
5. Humidity (Steady state)	Contact resistance: 40m ohms max. Insulation Resistance: 1000M ohms min.	96 hours at temperature of 40°C and humidity of 90% to 95%
6. Temperature Cycle	Contact resistance: 40m ohms max. Insulation Resistance: 1000M ohms min.	Tested for 5 cycles under following condition; Temperature : -55→ +5 to 35→ +85→ +5 to 35°C Time : 30→ 10 to 15→ 30→ 10 to 15 minutes
7. Durability (Insertion/withdrawal)	Contact resistance: 40m ohms max.	25 cycles
8. Salt spray	Contact resistance: 40m ohms max.	Exposed to density 5% salt water for 48 hours

■ Material

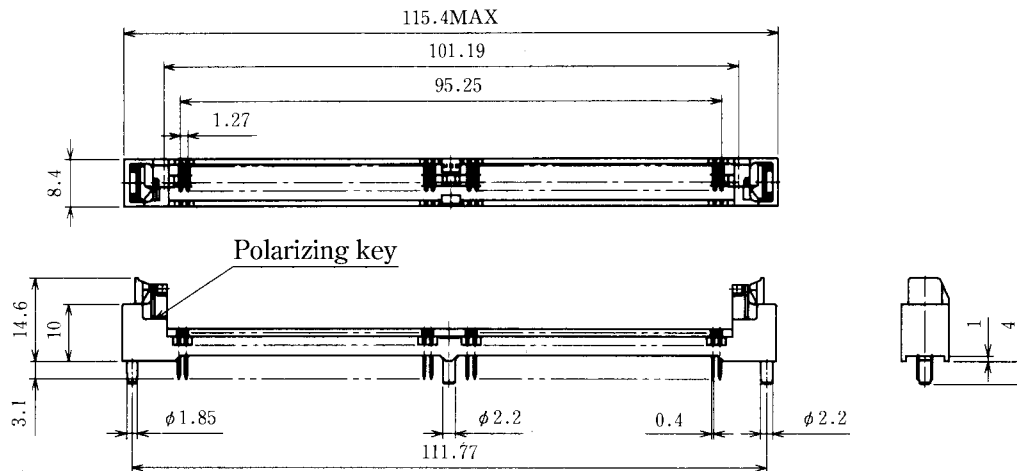
Part	Material	Finish
Contact	Phosphor copper	Selective gold plating
Insulator	PBT	UL94V-0

■ Ordering Information

SX3 LE - 72 S - 1.27 DSA
 ① ② ③ ④ ⑤ ⑥

① Series Name: SX3	⑤ Contact Pitch: 1.27mm
② Polarizing Key: LE: Left key	⑥ Contact type (row space x lead length) DSA: 2.54mm x 3.1mm
③ Number of Contacts: 72	
④ Contact Type: Female contact	

Left Key Type



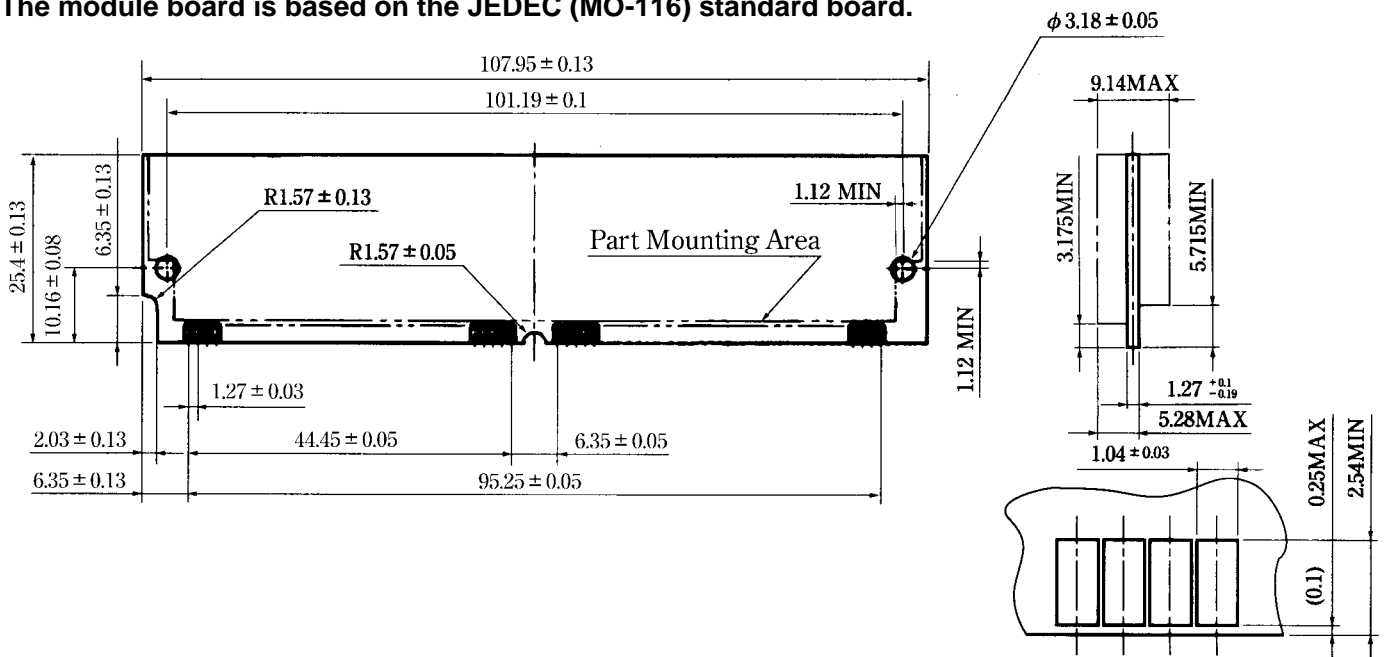
Part Number	CL No.	Contact Plating Spec.	Key	Number of Contacts
SX3LE-72S-1.27DSA	530-0210-6	Contact: Gold flash	Left	72

Note 1. The key corresponds to the JEDEC MO-116 polarizing key.

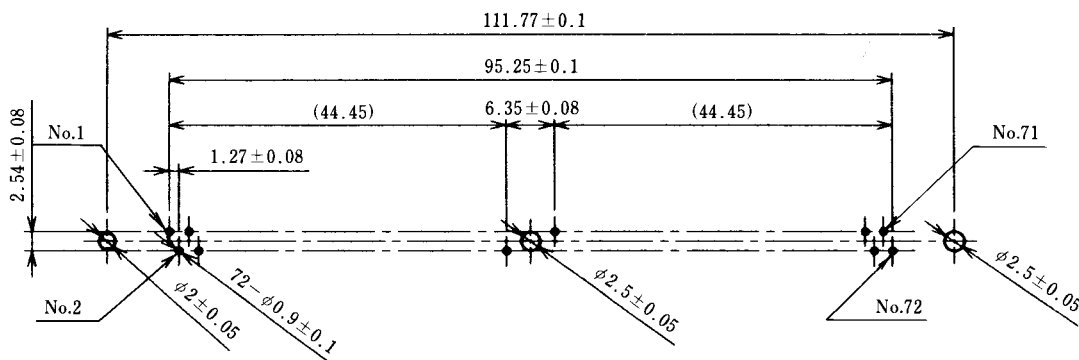
Note 2. When the 25.4mm height module board is used, the module board mounting height is 28mm.

Recommended Module Board Dimensions

The module board is based on the JEDEC (MO-116) standard board.



PCB mounting pattern



■ Operating Instruction

[Procedures for Board Insertion]

1. Adjust the socket polarizing key and the board key to the same direction.
2. Insert the board slantly. Moreover, lay the board at about 45° angle, and softly insert the board so as to hit the socket bottom. Stopping insertion halfway will result in improper insertion.

3. Raise the board, which has been inserted, and fix it to the latch position at both ends of the socket.

As soon as the board has passed through the latch claw head, a "click" tone is heard. With such a click, release hands. With this procedure, the board has been completely installed in the socket. At this time, the pressing force is equivalent to the extent of turning on an electric product switch. If the more force is needed, check whether the direction and depth to insert the board is adequate or not, and then re-push the board.

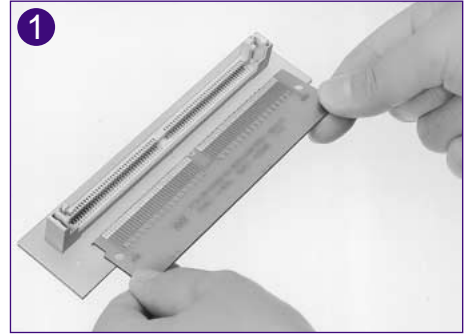
[Procedures for Board Extraction]

Apply the thumb nails to the latch knobs at both socket ends. Forcibly widen the latch knob to right and left ways and release the latch. Then, draw the board out along the angle where the board is raised.

Cautions

1. The latch has strength enough to endure. However, if force is applied according to other operation methods instead of the Procedures for Handling Sockets, products could be damaged.
2. The board is designed in compliance with JEDEC 72 SIMM . However, if other boards (specific board style, weight) are used instead of the recommended module board or if the mounting devices are used the other than memory IC, troubles due to vibration or other failures could occur. Confirm individual conditions.
3. Acute angles at pad edges of recommended module boards could cause failure in contacts. Therefore, it is recommended to offset the tie-bar (0.1mm) from the center line, set the internal pad, or remove sharp corners or burrs according to the recommended size ranges.
4. Stand-off is provided for measures to prevent flux rise, but resin sealing is not done. Confirm individual conditions.
5. If strong heat is concentrated on the product, the product will be deformed due to strength. If required, consult HRS company.
6. Use alcohol-based flux solvent, which is not affected by subject chemical reaction.
7. For sharp temperature variation or other reasons, if dews occur on the products, the product quality will be degraded. Take care of storage and applications.
8. Don't provide convex or concave portion at external edges of the module board, or and chamfer areas at both edges. Comply with the recommended sizes.
9. When two or more products are arranged for use, engage the module board in the manner to set the insertion side toward yourself and mount it sequentially from the depth.

Procedures for Board Insertion



Procedures for Board Extraction



10. It is recommended to specify an eccentricity between external edge (107.95) center and key (R1.57) center on the recommended module board to 0.1 maximum.
11. Insert the module board in parallel to the connector opening. If a strong resistance is perceived, re-insert the board. Note: the forced insertion could cause failure in the products.
12. If the connector is mounted horizontal to the direction, it is recommended to turn up the side to install the module board.
13. When two or more boards are arranged for use, it is recommended to specify the mounting pitch to 10.16mm or more. If the less than 10.16mm pitch is used, confirm individual conditions.
14. The dip portion tip is considered for safety, the tip is slimmed for enhancement of mountability. Be careful for handling dip portions.
15. Check the matching with individual module board, and confirm no problem.
16. The mounting height will increase under conditions of flow solder, board warpage, etc. Referring to the described values, check and use this product according to actual equipment.
17. Since this product does not correspond to reflow, check individual conditions for application.
18. Since this product is not specified for active cable insertion and extraction, be sure to insert or extract the memory module in the condition where unit power is turned off.
19. When the module board is engaged, check that the both board edges hook in the latch claws on the both sides, while left and right convex portions of the connector are firmly inserted in the round holes of module on both sides. Inadequate engagement (engagement as not described precedingly) could cause fuming, breakage, damage or contact failure in products. Take particular care for the insertion.
20. In order to install the module board, avoid the insertion to hold and rotate either board end only. For the board won't hook in the latches on the both side, or excessive force is applied to the connector or module board, which could cause failure or breakage of the product. Push the upper sides at both board edges at a time, and rotate the board so as to uniformly apply force to the latches.
21. If the memory module is not engaged in the board and exposed, dust will adhere to the opening area, which could cause malfunction, contact failure or damage to the product. Before the memory module engagement, be sure to thoroughly remove dusts on the connector.
22. Insert the module board along the guide (about 30 to 40°). If the module board is forcibly inserted in different directions, any trouble could occur.
23. For module board installation, if board corners hit the connector, the product could be deformed or damaged.
24. If this product is used for personal computers, peripheral equipment (printer, etc.), check individual conditions.

